

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Beiha Ma</td> <td>11/09/2011</td> </tr> <tr> <td>Uthamalingham Balachandran</td> <td>11/09/2011</td> </tr> <tr> <td>Shanshan Liu</td> <td>11/09/2011</td> </tr> <tr> <td>Manoj Narayanan</td> <td>11/09/2011</td> </tr> </tbody> </table>		Name	Execution Date	Beiha Ma	11/09/2011	Uthamalingham Balachandran	11/09/2011	Shanshan Liu	11/09/2011	Manoj Narayanan	11/09/2011
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<b>RECEIVING PARTY DATA</b>											
Name:	UChicago Argonne, LLC										
Street Address:	5801 S. Ellis Avenue										
City:	Chicago										
State/Country:	ILLINOIS										
Postal Code:	60637										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13250926</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13250926						
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Application Number:	13250926										
<b>CORRESPONDENCE DATA</b>											
Fax Number:	(312)621-0088										
Phone:	312-621-1330										
Email:	mail@cherskov.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	Michael J. Cherskov										
Address Line 1:	123 West Madison Street, Suite 400										
Address Line 4:	Chicago, ILLINOIS 60602										
ATTORNEY DOCKET NUMBER:	0003-02502										
NAME OF SUBMITTER:	Michael J. Cherskov										
Total Attachments: 3 source=assignment2502#page1.tif source=assignment2502#page2.tif source=assignment2502#page3.tif											

OP \$40.00 13250926

ASSIGNMENT

We, Beihai Ma of Naperville, Uthamalingam Balachandran of Willowbrook, Shanshan Liu of Naperville, and Manoj Narayanan of Woodridge, all in the State of Illinois, for good and valuable considerations to us in hand paid, the receipt and sufficiency whereof is hereby acknowledged, have sold, assigned, conveyed and set over, and do hereby sell, assign, convey and set over unto UChicago Argonne, LLC, having a place of business at 5801 South Ellis Avenue, Chicago, Illinois 60637, its successors and assigns, the entire right, title and interest in and to all subject matter invented or designed by us and disclosed in the patent application for the METHOD FOR FABRICATION OF CRACK-FREE CERAMIC DIELECTRIC FILMS, ANL-IN-11-010, filed in the U. S. Patent and Trademark Office on September 30, 2011 as Application Serial No. 13/250,926, executed by us, and any divisions and continuations thereof and in and to all Letters Patent of the United States, including any reissues and extensions thereof that may be obtained therefor, and the right, where such right can be legally exercised, in its own name to apply for and obtain Letters Patent, Inventor's Certificates, Utility Models and Designs, in countries foreign to the United States, including the full right to claim for any such application the benefits of the International Convention as fully and entirely as we could have done if the application had been in our names, and the entire interest in any Letters Patent, Inventor's Certificate, Utility Model or Design which may be granted on any such application in such foreign country; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent, Inventors Certificates, Utility Models or Designs, on applications as aforesaid, to issue any and all Letters Patent, Inventor's Certificates, Utility Models and Designs that may be granted for said invention to said UChicago Argonne, LLC, its successors and assigns.

And for the above-named considerations, we hereby agree that we will without additional compensation but without cost to ourselves, promptly communicate to UChicago Argonne, LLC, its successors and assigns, any facts known to us respecting said invention whenever requested, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications for Letters Patent, Inventor's Certificates, Utility Models and Designs and assignments thereof, make all rightful oaths and generally do everything possible to aid said assignee, its successors and assigns, as and when requested by them, in obtaining and enforcing proper Letters Patents, Inventor's Certificate, Utility Model and Design protection for said invention or inventions and improvements, in the United States and in all other countries.

Dated: Nov. 9, 2011

Beihai Ma  
Beihai Ma

Dated: NOV. 9, 2011

Uthamalingam Balachandran  
Uthamalingam Balachandran

Dated: NOV. 9, 2011

Shanshan Liu  
Shanshan Liu



ASSIGNMENT

I, Sheng Chao of Greensburg, PA, for good and valuable considerations to me in hand paid, the receipt and sufficiency whereof is hereby acknowledged, have sold, assigned, conveyed and set over, and do hereby sell, assign, convey and set over unto UChicago Argonne, LLC, having a place of business at 5801 South Ellis Avenue, Chicago, Illinois 60637, its successors and assigns, the entire right, title and interest in and to all subject matter invented or designed by me and disclosed in the patent application for the METHOD FOR FABRICATION OF CRACK-FREE CERAMIC DIELECTRIC FILMS, ANL-IN-11-010, filed in the U. S. Patent and Trademark Office on September 30, 2011 as Application Serial No. 13/250,926, executed by me, and any divisions and continuations thereof and in and to all Letters Patent of the United States, including any reissues and extensions thereof that may be obtained therefor, and the right, where such right can be legally exercised, in its own name to apply for and obtain Letters Patent, Inventor's Certificates, Utility Models and Designs, in countries foreign to the United States, including the full right to claim for any such application the benefits of the International Convention as fully and entirely as I could have done if the application had been in my name, and the entire interest in any Letters Patent, Inventor's Certificate, Utility Model or Design which may be granted on any such application in such foreign country; and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent, Inventors Certificates, Utility Models or Designs, on applications as aforesaid, to issue any and all Letters Patent, Inventor's Certificates, Utility Models and Designs that may be granted for said invention to said UChicago Argonne, LLC, its successors and assigns.

And for the above-named considerations, I hereby agree that I will without additional compensation but without cost to myself, promptly communicate to said UChicago Argonne, LLC, its successors and assigns, any facts known to me respecting said invention whenever requested, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications for Letters Patent, Inventor's Certificates, Utility Models and Designs and assignments thereof, make all rightful oaths and generally do everything possible to aid said assignee, its successors and assigns, as and when requested by them, in obtaining and enforcing proper Letters Patents, Inventor's Certificate, Utility Model and Design protection for said invention or inventions and improvements, in the United States and in all other countries.

<u>Sheng Chao</u>	<u>11/10/2011</u>		
Sheng Chao	Date		
<u>(WITNESS SIGNATURE)</u>	<u>11/10/2011</u>	<u>DEV BANERJEE</u>	
	Date	PRINT WITNESS NAME	Date